

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

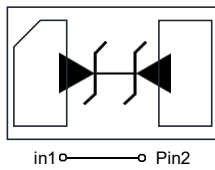


PLED

Product data sheet



DFN1610-2L



Marking D5N

Feature

- 1500W Peak pulse power per line ($t_P = 8/20\mu s$)
- DFN1610-2L package
- Response time is typically $< 1\text{ ns}$
- Protect one I/O or power line
- Low clamping Voltage
- RoHS compliant
- Transient protection for data lines to
IEC 61000-4-2(ESD) $\pm 30\text{KV}$ (air), $\pm 30\text{KV}$ (contact);
IEC 61000-4-4 (EFT) 40A (5/50ns)

Applications

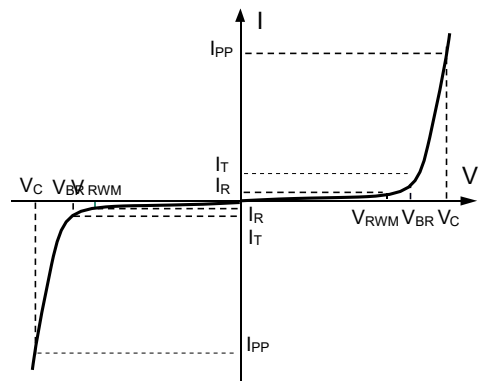
- Cell phone handsets and accessories
- Personal digital assistants (PDA's)
- Notebooks, desktops, and servers
- Portable instrumentation
- Cordless phones
- Digital cameras
- Peripherals
- MP3 players

Mechanical Characteristics

- Lead finish:100% matte Sn(Tin)
- Mounting position: Any
- Qualified max reflow temperature:260°C
- Pure tin plating: 7 ~ 17 μm
- Pin flatness : $\leq 3\text{mil}$
- Device meets MSL 3 requirements

Electronics Parameter

Symbol	Parameter
V_{RWM}	Peak Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
P_{PP}	Peak Pulse Power
C_J	Junction Capacitance



Electrical characteristics per line@25°C (unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Peak Reverse Working Voltage	V_{RWM}				5.0	V
Breakdown Voltage	V_{BR}	$I_t = 1mA$	5.5		7.5	V
Reverse Leakage Current	I_R	$V_{RWM} = 5V T=25^{\circ}C$			1.0	μA
Clamping Voltage	V_C	$I_{PP}=20A t_P = 8/20\mu s$		8.0	10	V
Clamping Voltage	V_C	$I_{PP}=50A t_P = 8/20\mu s$		9.0	11	V
Clamping Voltage	V_C	$I_{PP}=100A t_P = 8/20\mu s$		10	12	V
Clamping Voltage	V_C	$I_{PP}=140A t_P = 8/20\mu s$		11	13	V
Junction Capacitance	C_j	$V_R=0V f = 1MHz$		400	450	pF

Note

- 1) VRWM is the maximum reverse working voltage, or reverse stand-off voltage. ESD can protect signal line properly within its rated voltage. If the signal line's voltage is over VRWM, ESD will change to other state.

Absolute maximum rating@25°C

Rating	Symbol	Value	Units
Peak Pulse Power ($t_P = 8/20\mu s$)	P_{PP}	1500	W
Peak Pulse Current ($t_P = 8/20\mu s$)	I_{PP}	140	A
Lead Soldering Temperature	T_L	260 (10 sec)	$^{\circ}C$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^{\circ}C$

Typical Characteristics

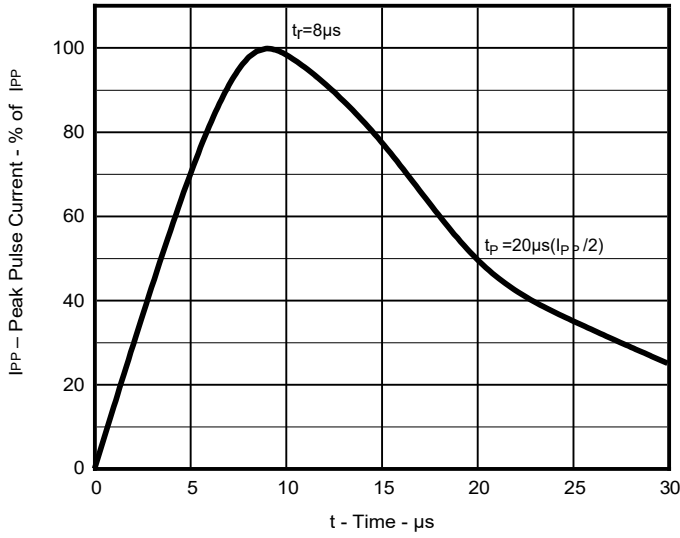


Fig 1. Pulse Waveform(8/20μs)

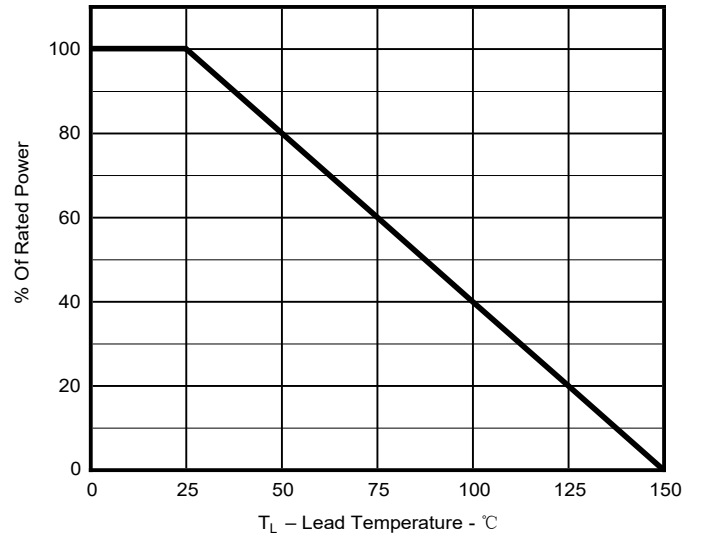


Fig 2. Power Derating Curve

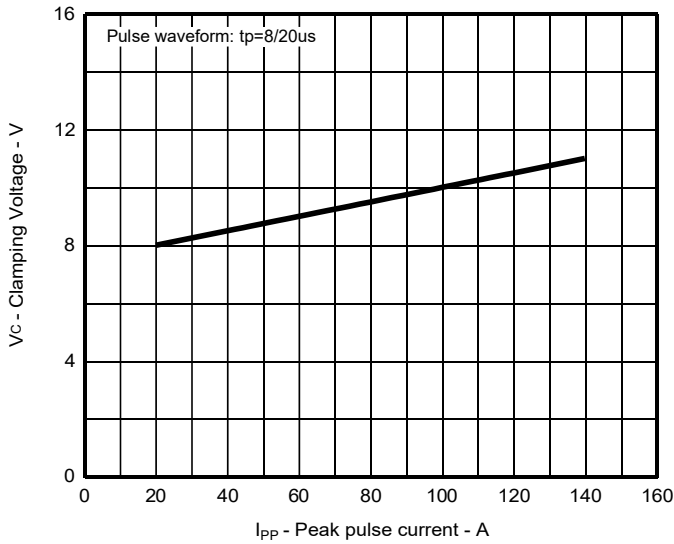


Fig 3. Clamping voltage vs. Peak pulse current

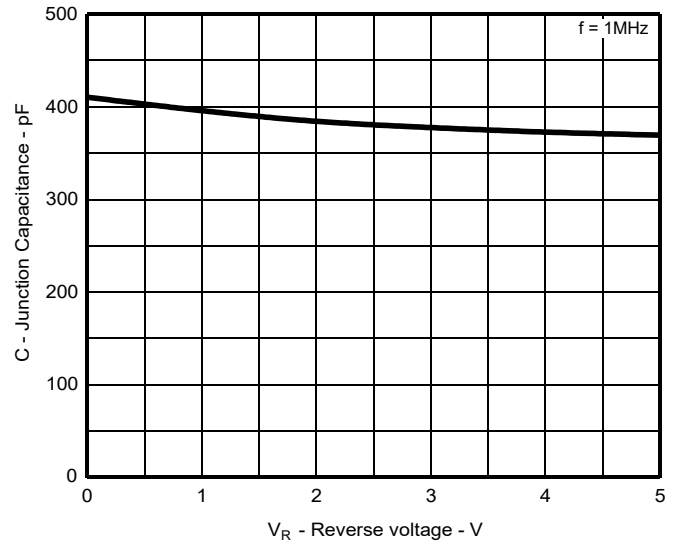


Fig 4. Capacitance vs. Reverse voltage

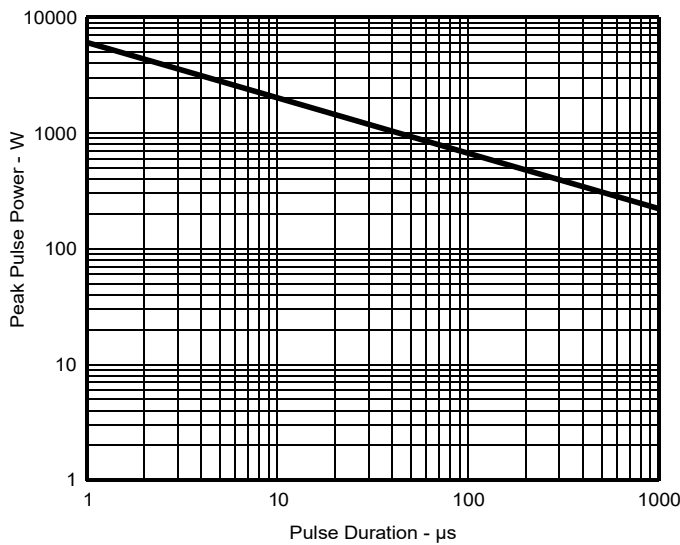
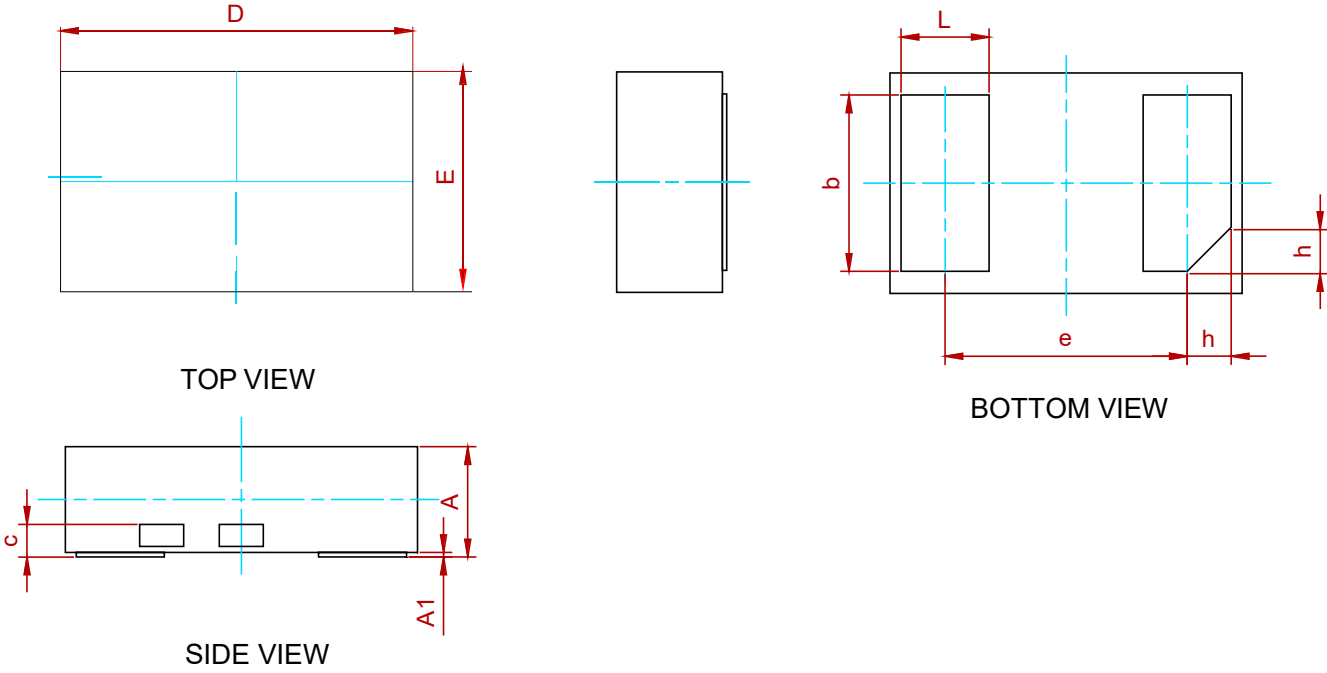


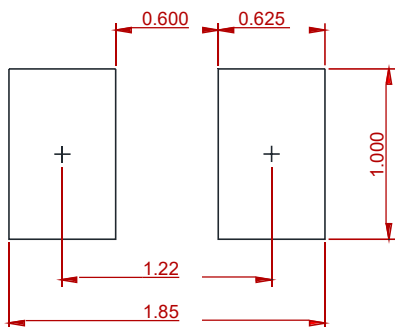
Fig 5. Non Repetitive Peak Pulse Power vs. Pulse time

PACKAGE MECHANICAL DATA



Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.45	0.50	0.55
A1	0.00	0.02	0.05
c	0.15 Ref.		
b	0.75	0.80	0.85
L	0.35	0.40	0.45
D	1.55	1.60	1.65
E	0.95	1.00	1.05
e	1.10 BSC		
h	0.20 Ref.		

Recommend PCB Layout (Unit: mm)



Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

REEL SPECIFICATION

P/N	PKG	QTY
PTVSHC2EN5VB-MS	DFN1610-2L	3000

Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringement of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.